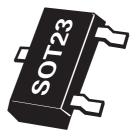
### **40V SILICON HIGH CURRENT LOW LEAKAGE SCHOTTKY DIODE**

#### **SUMMARY**

Schottky Diode  $V_R$  = 40V;  $I_F$  = 1.16A;  $I_R$  = 20 $\mu$ A

#### **DESCRIPTION**

This compact SOT23 packaged Schottky diode offers users an excellent performance combination comprising high current operation, extremely low leakage and low forward voltage ensuring suitability for applications requiring efficient operation at higher temperatures (above 85°C) see Operational Efficiency chart on page 4.



Cathode

#### Key benefits:

Performance capability equivalent to much larger packages

Improved circuit efficiency & power levels

PCB area savings

#### **FEATURES**

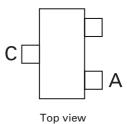
- Low equivalent on resistance
- Extremely low leakage (20μA @30V)
- High current capability (I<sub>F</sub> = 1.16A)
- Low V<sub>F</sub>, fast switching Schottky
- SOT23 package
- ZLLS1000 complements low temperature equivalent ZHCS1000
- Package thermally rated to 150°C

#### **APPLICATIONS**

- DC DC converters
- Strobes
- Mobile phones
- · Charging circuits
- Motor control

#### **ORDERING INFORMATION**

DEVICE	REEL (inches)		QUANTITY PER REEL
ZLLS1000TA	7	8mm embossed	3000 units
ZLLS1000TC	13	8mm embossed	10000 units



Anode

### **DEVICE MARKING**

L10



#### **ABSOLUTE MAXIMUM RATINGS**

PARAMETER		SYMBOL	VALUE	UNIT
Schottky diode		•	•	
Continuous reverse voltage		V <sub>R</sub>	40	V
Forward current	I <sub>F</sub>	1.16	А	
Peak repetitive forward current		I <sub>FPK</sub>	1.88	А
Rectangular pulse duty cycle				
Non repetitive forward current	t=≤100μs	I <sub>FSM</sub>	22	A
	t=≤10ms		6.4	Α
Package			·	·
Power dissipation at T <sub>amb</sub> =25°C single die continuous		P <sub>D</sub>	625	mW
single die measured at t<5 secs			840	mW
Storage temperature range		T <sub>stg</sub>	-55 to +150	°C
Junction temperature		Тј	150	°C

### THERMAL RESISTANCE

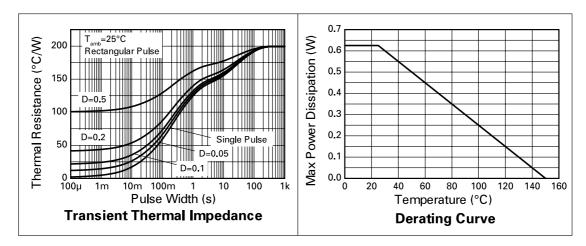
PARAMETER	SYMBOL	VALUE	UNIT
Junction to ambient (a)	$R_{\Theta JA}$	200	°C/W
Junction to ambient (b)	$R_{\Theta JA}$	149	°C/W

### Notes

- (a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
- (b) For a device surface mounted on FR4 PCB measured at t<5secs.



### **TYPICAL CHARACTERISTICS**





#### **ELECTRICAL CHARACTERISTICS** (at Tamb = 25°C unless otherwise stated)

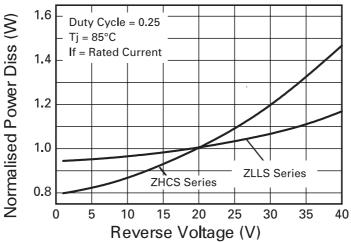
SCHOTTKY DIODE CHARACTERISTICS						
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Reverse breakdown voltage	V <sub>(BR)R</sub>	40			V	I <sub>R</sub> =500μA
Forward voltage	V <sub>F</sub>		280	310	mV	I <sub>F</sub> =50 mA*
			310	340	mV	I <sub>F</sub> =100 mA*
			355	390	mV	I <sub>F</sub> =250mA*
			405	460	mV	I <sub>F</sub> =500mA*
			450	510	mV	I <sub>F</sub> =750mA*
			490	560	mV	I <sub>F</sub> =1A*
			570	660	mV	I <sub>F</sub> =1.5A*
			475		mV	I <sub>F</sub> =1000mA*,Ta = 100°C
Reverse current	I <sub>R</sub>		11	20	μΑ	V <sub>R</sub> =30V
			750		μΑ	$V_R = 30V, Ta = 85^{\circ}C$
Diode capacitance	C <sub>D</sub>		26		pF	f=1MHz,VR=30V
Reverse recovery time	t <sub>rr</sub>		4		ns	Switched from
Reverse recovery charge	O <sub>rr</sub>		335		nC	$I_F$ = 500mA to $V_R$ = 5.5V Measured @ $I_R$ 50mA. di /d t = 500mA/ ns. Rsource = 6 $\Omega$ ;Rload= 10 $\Omega$

<sup>\*</sup>Measured under pulsed conditions. Pulse width = 300 $\mu$ S. Duty Cycle  $\leq$  2%.

#### **Operational Efficiency chart**

The operational efficiency chart indicates the beneficial use of the ZLLS Series diodes in applications requiring higher voltage, higher temperature operation. Circuits requiring Low voltage Low temperature operation will benefit from using Zetex

low V<sub>F</sub> ZHCS

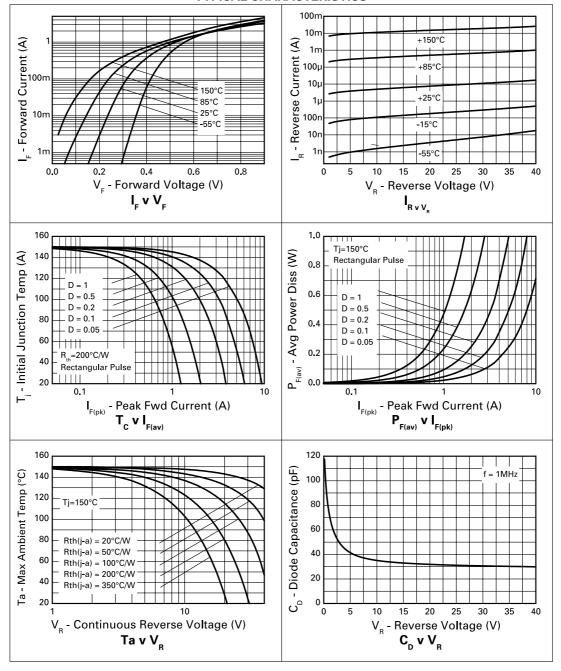


# **Operational Efficiency Example**



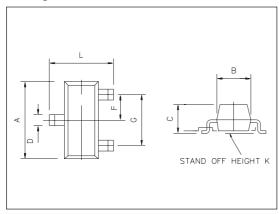
Series diodes.

### **TYPICAL CHARACTERISTICS**

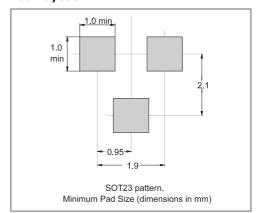


**ZETEX** 

### **Package Outline**



### **Pad Layout**



### **Package Dimensions**

DIM	Millin	neters	Inches		
	Min.	Max.	Min.	Max.	
Α	2.67	3.05	0.105	0.120	
В	1.20	1.40	0.047	0.055	
С	-	1.10	-	0.043	
D	0.37	0.53	0.0145	0.021	
F	0.085	0.15	0.0033	0.0059	
G	NOM	1 1.9	NOM	0.075	
К	0.01	0.10	0.0004	0.004	
L	2.10	2.50	0.0825	0.0985	

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